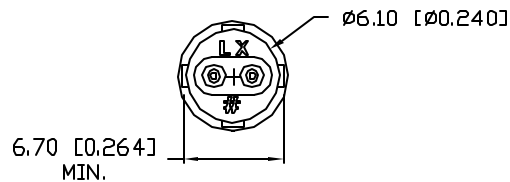
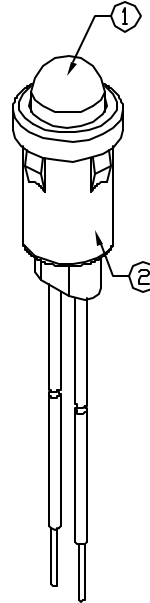
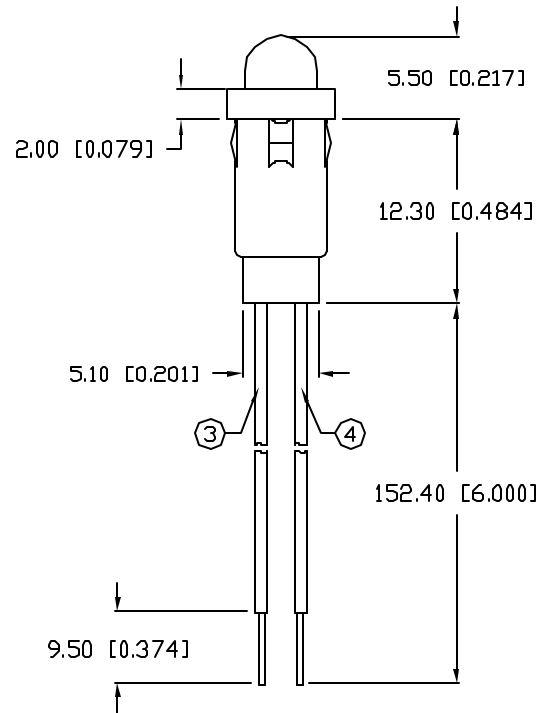
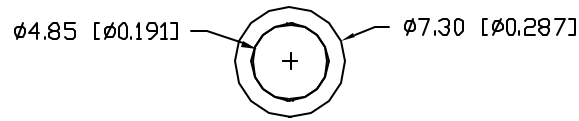


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PART NUMBER
SSI-LXH600SID-150

REV.



PANEL HOLE: $\varnothing 0.250^*$
PANEL THICKNESS: 0.030" MIN.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		100		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX509F3SID LED.
2. SSH-LXH600 HOLDER, BLACK.
3. ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, TOP OVERCOAT, RED INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.
4. CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, TOP OVERCOAT, BLACK INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= $\frac{+DECIMAL PRECISION}{-0.00}$, MAX= $\frac{+0.00}{-DECIMAL PRECISION}$

REV.

PART NUMBER

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T-5mm (T-1 3/4) LED, PANEL MOUNT INDICATOR,
636nm SUPER HIGH INTENSITY RED LED, RED DIFFUSED LENS,
WITH 6" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

GT

CHECKED BY:

APPROVED BY:

DATE: 7.25.01

PAGE: 1 OF 1

SCALE: N/A